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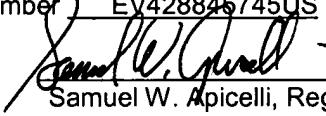
OFFICE OF PETITIONS

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I hereby certify that these documents, namely a Response and Amendment, Petition, and a Supplemental IDS with references, in connection with the above-identified Patent Application, are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service on the date indicated below and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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Date of Deposit 9/10/04


Samuel W. Apicelli, Reg. No. 36,427



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of: Che-Yu Li

Serial No.: 10/736,280 Examiner: Leon, Edwin A.

Filed: 15 December 2003 Group Art Unit: 2833

For: ELECTRICAL CONTACT

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop DD
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the Duty of Disclosure set forth in 37 CFR 1.56, the materials listed on the enclosed form PTO-1449 are hereby brought to the attention of the Examiner. A copy of each is enclosed.

This Information Disclosure Statement is submitted prior to the mailing date of the first Office Action on the merits received by Applicant in the above-identified application.

The claimed invention is patentable over the enclosed references. No representations are made regarding the references other than those set forth above.

Form PTO-1449 U.S. Department of Commerce Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION (Use several sheets if necessary)	Docket No.	H1823-00004	Serial No.	10/736,280
	Applicant:	Che-Yu Li		
	Filing Date:	15 December 2003	Group Art Unit	Unassigned

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U.S. PATENT DOCUMENTS

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*EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	OFFICE OF PETITIONS		FILING DATE IF APPROPRIATE
				CLASS	SUBCLASS	
	3,354,260	November 1967	E. D. Brandt et al.			
	3,452,149	June 1969	F. J. Rinaldi			
	3,639,978	February 1972	Schurman			
	3,711,627	January 1973	Maringulov			
	3,800,378	April 1974	Lee et al.			
	4,781,640	November 1988	Tornoe et al.			
	6,298,551	October 2001	Wojnarowski et al.			
	6,312,266	November 2001	Fan et al.			
	6,663,399	December 2003	Ali et al.			
	6,695,623	February 2004	Brodsky et al.			
	6,712,620	March 2004	Li et al.			
	US 0221/0024735	September 2001	Kuhlmann-Wilsdorf et al.			
	US 2002/0106913	August 2002	Schuenemann et al.			
	US 2003/0049974	March 2003	Bauer et al.			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER (Including Author, Title, Date, Pertinent Pages, Etc.)

	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN; <i>Interposer Carrier</i> ; January 1987; pp3678 – 2680
	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN; <i>Improved Interconnection Structure</i> ; November 1988; pp17 – 19

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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U.S. PATENT DOCUMENTS

*EXAMINER INITIALE	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	US 2003/0176083	September 2003	Li et al.			
	US 2003/0207608	November 2003	Weiss			
	US 2004/0053519	March 2004	Li et al.			
	US 2003/0073329	April 2003	Beaman et al.			
	US 2003/0134525	July 2003	Sweetland et al.			

FOREIGN PATENT DOCUMENTS

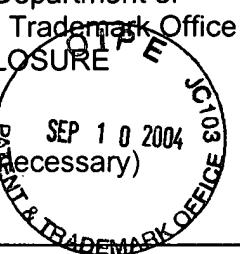
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	NO

OTHER (Including Author, Title, Date, Pertinent Pages, Etc.)

	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN, <i>Special Thermal Conductive Interposers</i> , September 1993
	Internet page of delphion.com; IBM TECHNICAL DISCLOSURE BULLETIN; <i>High Density Area Array Connector</i> ; April 1991; Pub. No. 324

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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	NO

OTHER (Including Author, Title, Date, Pertinent Pages, Etc.)

	Solid State Technology; <i>Integrating Backend Processes</i> ; February 2001; pp78 - 85
	HCD, Inc.; <i>Two Fundamental Approaches to Enabling High Performance LGA Connections</i> ; pp508 - 514
	HDC, Inc.; <i>An Adaptable, High Performance LGA Connector Technology</i>
	Internet page of Tecknit Interconnection Products; <i>Standard Fuzz Button Contacts</i>
	Internet page of Tecknit Interconnection Products; <i>Fuzz Button Contacts</i>
	Internet page of Cinch; <i>High-Speed Interconnect Technology</i>
	Internet page of COSMOS; <i>COSMOS helps analyze circuit board connectors</i>
	HDC, Inc.; <i>SuperButton Land Grid Array (LGA) Connectors</i> ; 6/2003
	Internet page of Design News.com; <i>PC-nonlineare FEA makes the connection</i> ; John Lewis; September 18, 2000
	A <i>High Density Ian Grid Array Connector for MCM's</i> ; M. E. St. Lawrence and S. S. Simpson pp1491 – 1511
	International Symposium on Microelectronics; <i>Z-Axis Interconnection for 3-D High Density Packaging</i> ; S. Spiesshoefer et al.; pp167 - 171
	HDC; <i>Corporate Overview</i> ; June 2003
	A <i>novel Elastomeric Connector for Packaging Interconnections, Testing and burn-in Applications</i> ; D. Y. Ehih et al.
	<i>Button Contacts for liquid Nitrogen Applications</i> ; Frank Almquist

EXAMINER**DATE CONSIDERED**

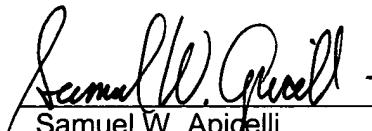
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Serial No. 10/736,280

The Examiner is requested to acknowledge consideration of the information provided in this paper in accordance with prescribed procedures.

Respectfully submitted,

Date: 9/10/04



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Docket No. H1823-00004